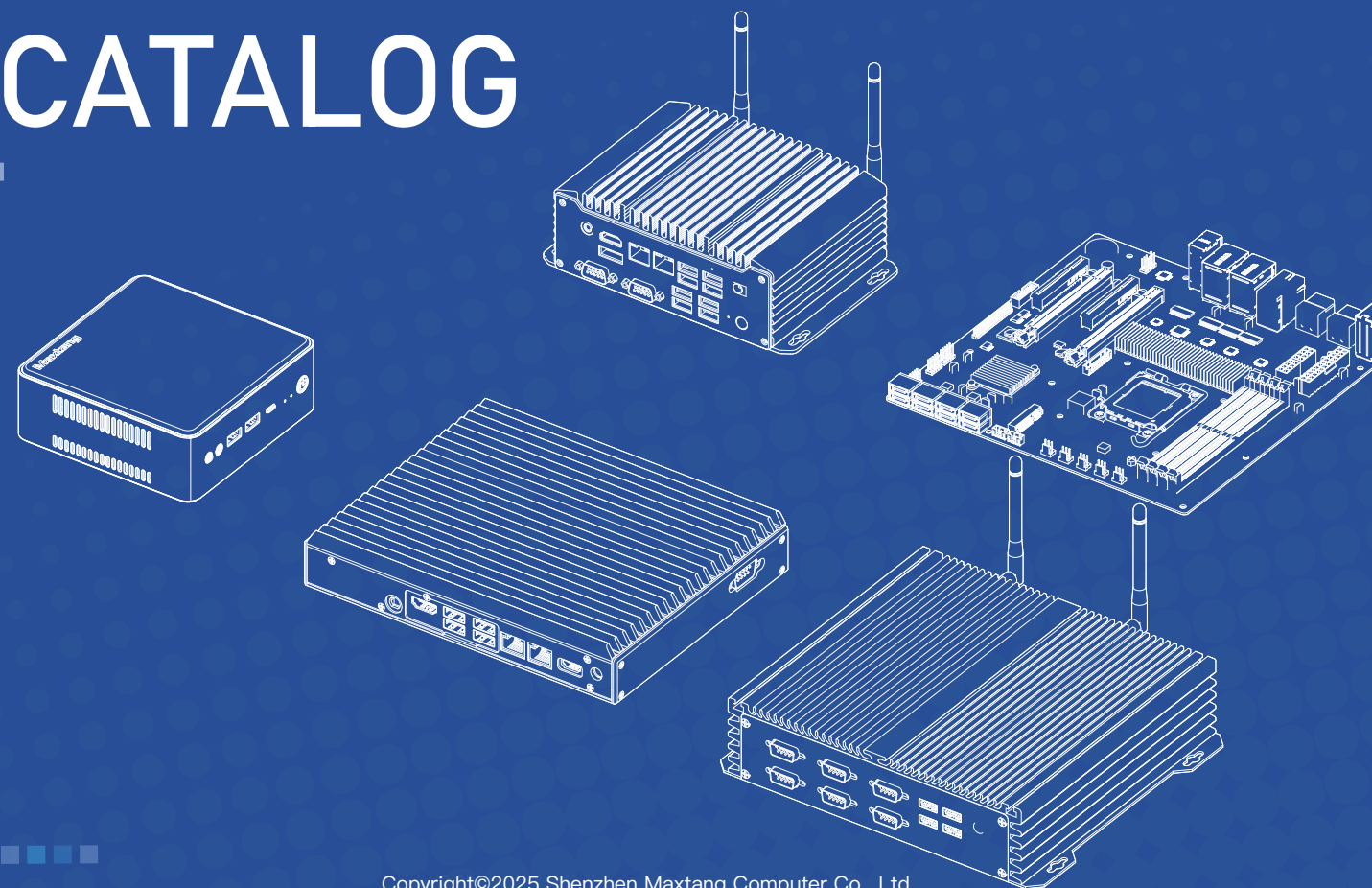


PRODUCT CATALOG

MAXIMIZING YOUR COMPUTING PRODUCTIVITY



Shenzhen Maxtang Computer Co., Ltd.
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<https://www.maxtangpc.com> <https://store.maxtangpc.com>



Founded in 2009, Maxtang specializes in industrial computers, motherboards, and embedded solutions, integrating research, development, manufacturing, and sales, located in Shenzhen, China. Our mission is to establish a strong brand through innovative designs and unparalleled customer satisfaction. We are committed to delivering cutting-edge PCs and motherboards to enterprises and individual users worldwide.

As an associate member of the Intel® IoT Solutions Alliance and a member of the Industrial Solution Builders Specialist, Maxtang has earned the prestigious "China National High & New Technology Enterprise" qualification. Our products are environmentally friendly and comply with CE, WEEE, RoHS legislation, and ISO9001:2015 certification standards.



At Maxtang, we specialize in customized solutions for a wide range of industrial applications, including surveillance, digital signage, POS edge computing, and industrial automation. Committed to excellence, we take pride in delivering high-quality products and exceptional customer support.

As a trusted IIoT technology partner, we collaborate with Intel®, AMD, and a robust ecosystem of hardware and software providers to drive innovation, connectivity, and growth. Our expertise enables us to offer flexible, high performance, and future-ready solutions that address the most complex industry challenges. At Maxtang, we are more than just a vendor—we are industrial IoT specialists.

1500+

Over 1500+ Customers Worldwide

15+

Over 10 Years of Professional Experience

500+

Over 500 employees, including 50+ R&D engineers and designers

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Part one

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Part two

Motherboard

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Part three

System

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Content

Industry Influence

Maxtang has significantly broadened its global market presence through participation in various trade shows, such as CES(Consumer Electronics Show), Integrated Systems Europe, Embedded World Germany, India Expo Convergence, and COMPUTEX in Taiwan. Through those conferences and tradeshow, Maxtang has shown its engagement and visibility to its partners with the innovation capability in industry IoT solutions.



SINCE 2009

2009

- May 2009: Founded in Shenzhen, China; Launched Low-TDP Atom-based motherboards

2012

- Aug 2012: Launched the first fanless industrial PC.
- Jun 2012: Established Maxtang Hong Kong Branch.

2013

- Jan 2013: Launched 3rd Gen Intel Core-based products.

2016-2017

2014-2015

- Oct 2015: Won "Intel Innovative Technology" Award.
- Feb 2015: Launched Broadwell/Braswell-based products; Won "Best Digital Signage Player Brand Award."
- May 2014: Launched Bay Trail-based products.
- Aug 2014: Launched H81 platform-based products.
- Sep 2014: Launched Haswell-based products.

2018-2019

2020-2021

- Oct 2019: Launched 8th Gen Intel Core-based products.
- May 2019: Announced future development strategy on tenth anniversary; Launched first PoE product.
- Apr 2019: Partnership with SANTSU SANGYO CO., Ltd.
- Jan 2019: Launched Apollo Lake-based mini-PC.
- Mar 2018: Entered the industrial control industry.

- Nov 2017: Passed ISO9001 certification.
- Sep 2017: Launched the first AI industrial camera with Intel.
- Mar 2017: Launched Kabylake-based products.
- Dec 2016: Launched Skylake-based products.
- Nov 2016: Won "China National High-Tech Enterprise" Award.

2022

- Feb 2022: Launched Elkhart Lake-based products.
- Jun 2022: Launched Alder Lake-based product.

- Dec 2021: Launched Gemini Lake-based ultra-compact mini-PC.
- Sep 2021: Launched Jasper Lake-based products.
- Apr 2021: Launched 11th Gen Intel Tiger Lake-based products.
- Apr 2020: Partner with "OITECH" to expand business in the industrial computer field.

2023-2025

Timeline

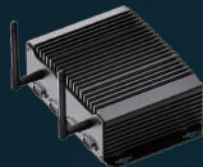
Applications

We specialize in delivering customized solutions and products that cater to diverse industrial requirements, complemented by our professional services. Our areas of expertise include:

- IoT Solutions
- Energy Management
- Surveillance
- Data Storage
- Communication
- Network Security
- Digital Signage
- Edge Computing
- Industrial Automation
- Smart Transportation
- Self-Service Terminals
- In-Vehicle Computing



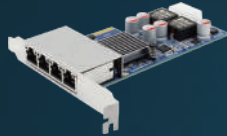
03
Machine Vision



04
Industrial PCs



05
Motherboards



06
PoE/PCIe Extension Cards



01
Mini PCs



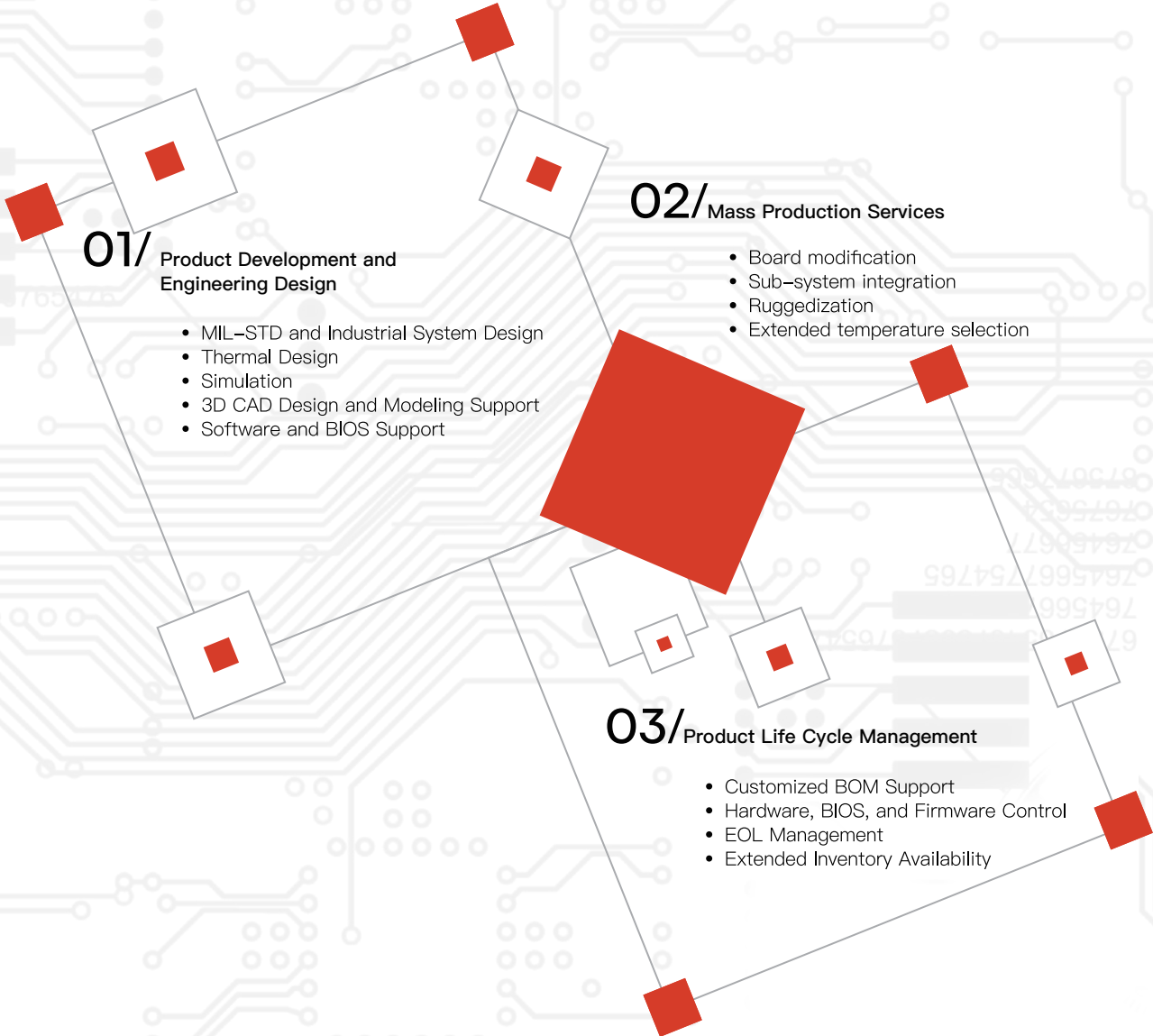
02
Phoenix Hill Module Kit



07
RTOS (Real-time operating system)

Product Type

Professional Support



01/ Excellence in Engineering Technology

- Experienced engineers analyze PCB designs and prototypes for optimal results.
- Efficient testing plans ensure thorough analysis and exceptional product delivery.
- Senior engineers excel in process quality planning and implementation.



02/ Stringent Quality Control

- Utilize advanced SPI+AOI optical inspection equipment for 100% quality assurance.
- Monitor process quality at every stage for superior performance.
- Hold dual quality management system certifications for continuous improvement.



03/ High-Quality Materials Use

- Use ALPHA brand lead-free solder paste and high-purity solder wire for optimal results.
- Source materials from trusted suppliers like Yuntie.
- Avoid secondary processed materials for superior product quality.



04/ Precise Quality Control

- Conduct rigorous inspection of incoming and outgoing materials.
- Perform pre-production, in-process, and post-production quality testing.
- Ensure excellence through thorough quality analysis and confirmation.



05/ Comprehensive Manufacturing Process

- Commitment to timely delivery, high quality, and customer-centric approach.
- Provide value-added after-sales services for customer satisfaction.
- Offer integrated one-stop solution services for a seamless experience.



06/ Professional and Highly Skilled Team

- Team of highly qualified professionals dedicated to delivering excellence.
- Over 90% of employees hold advanced degrees in our R&D department.
- Possess exceptional execution capabilities and strive for continuous improvement.



Optical automatic electronic inspection equipment-Blueeye FI600/2 sets



12 zones Dual Rail SMT Reflow Oven KTR-1200D/2 sets



High-speed automatic optical inspection equipment AOI JTA-680D/2 sets



High-speed printer Densen Hito/2 sets



Intelligent high-speed placement machine Panasonic NPMD3/6 sets



Intelligent multi-functional placement machine Panasonic NPMTT 2/2 sets



Automated offline AOI-JTA-680D/2 sets



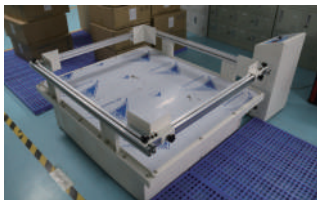
High-speed automatic optical inspection equipment SPI Jintuo JTREFINE-C/2 sets



Double wave soldering equipment Mindray Mairay/2 sets



Automated BGA automatic welding equipment Zhuo Mao ZMR6200/2 sets



Automatic simulation transportation vibration table DK5024/1 set



Automatic unloading machine ULF-390A2/1 set

Manufacturing Capabilities

Maxtang's manufacturing facility is strategically located in Huihuang Industrial Park, Guangming District, Shenzhen. We aim to become a reliable and trusted supplier of industrial computers for global customers. We have meticulously designed our manufacturing facility with flexible layouts and expansion capabilities, ensuring we can effectively address the growing demand for production capacity. And we have developed an efficient production system by leveraging the expertise of our professional and experienced personnel. The system enables us to promptly respond to customer requests, whether for standard or customized boards and systems.

Honors and Awards

Industry Recognition & Awards

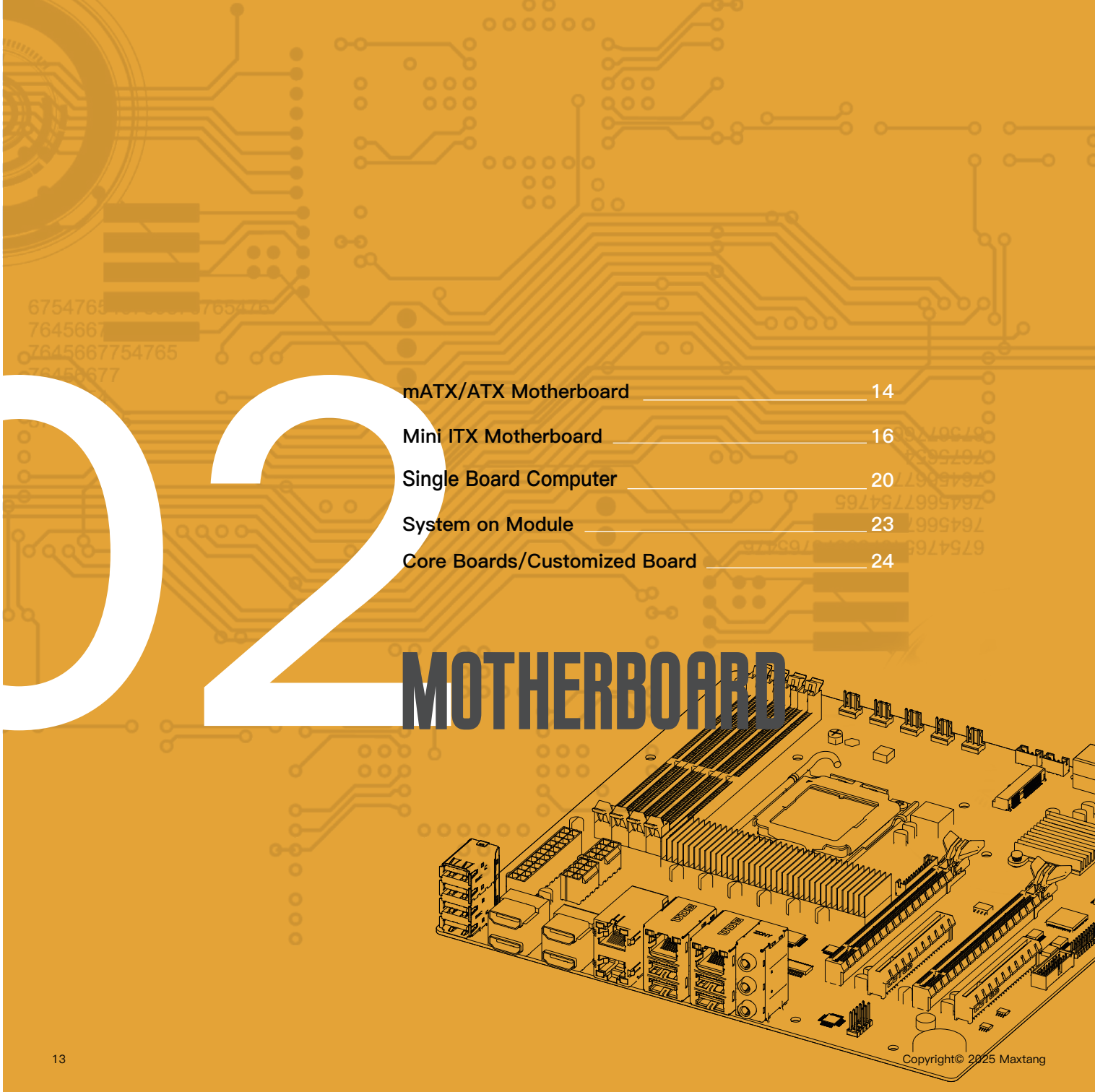
- Holders of the Industrial Control Host Patent and Product Patent
- Advanced research and development to stay ahead of industry trends
- China National High & New Technology Enterprise Award
- Digital Signage Player Brand Award
- Intel Innovative Technology Award
- RoHS, FCC, CE, and 3C Certified
- ISO 9001



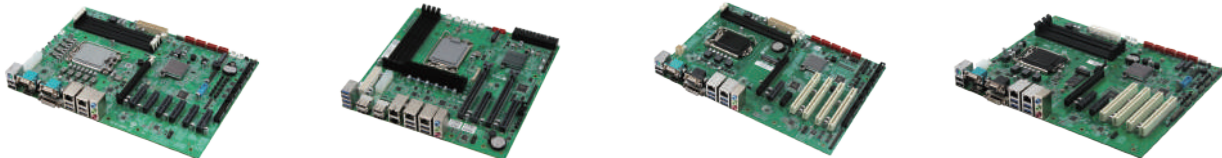
Why Choose Maxtang?

- Award-Winning Innovation
- Certified Quality & Global Compliance
- Trusted by Global Partners & Clients
- Industry-Leading R&D & Patented Technology
- Tailored Solutions for Businesses & Enterprises





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Model								
mATX/ATX Motherboard								
	ALD-75	ALD-76	HWD-75	SKD-75	HWD-70	KLD-70	ARD-75	
CPU		Intel® Alder Lake–S/Raptor Lake (LGA1700)Processor with Q670/H670/Z690 Chipset	Intel® Alder Lake–S/Raptor Lake (LGA1700)Processor with Z690 Chipset	Intel® Haswell (LGA1150) Processor with B85 Chipset	Intel® 6th,7th,8th,9th Gen (LGA1151) Processor with Q170 Chipset	Intel® Haswell (LGA1150) Processor with B85 Chipset	Intel® 6th,7th,8th,9th Gen Processor with H110 Chipset (LGA1151)	Intel® Arrow Lake (LGA1851) Processor with Z890 Chipset
Memory		4x UDIMM DDR4 up to 128GB	4x UDIMM DDR5 up to 128GB	2x SO–DIMM DDR3 up to 32GB	4x UDIMM DDR4 up to 64GB	2xSO–DIMM DDR3 up to 16GB	2x SO–DIMM DDR4 Up to 64GB	4x UDIMM DDR5 up to 192GB
Display via		1x HDMI®, 1x DVI–I(VGA)	4x HDMI®, 1x VGA*onboard pin	1x HDMI®, 1x VGA, 1x DVI	1x HDMI®, 1x VGA,1x DVI	1x HDMI®, 2x VGA(1*onboard pin), 1x DVI–D	1x HDMI®, 1x VGA, 1x DVI–D, 1x VGA(Onboard Pin)	1x HDMI®, 1x DVI–I
Storage		1x M.2_2280 NVMe (PCIe4.0)/SATA, 4x SATA	1x M.2_2280 NVMe (PCIe4.04X) SSD, 8x SATA3.0, Support RAID 0. 1. 5. 10	1x mSATA, 5x SATA(SATA4, 5 are SATA2.0 Definition)	1x M.2_2280/2242 SATA, 5x SATA (Support RAID 0,1,5,10)	1x mSATA 1x SATA2.0, 3x SATA3.0	1x mSATA 3x SATA3.0	1xM.2_2280 NVMe(P–Cle4.0)/SATA, 4xSATA
Size		304.8mm x 218.44mm	243.84mm x 243.84mm	305mm x 207mm	305mm x 244mm	244mm x 200mm	243.84mm x 203mm	304.8mm x 218.44mm
Power		ATX 24pin + 2*8pin	ATX 24pin + 2*8pin	ATX 24pin + 4pin	ATX 24pin + 8/4pin	ATX 24pin + 4pin	ATX 24pin + 4pin	ATX 24pin + 2x8pin
Operating Temp		0°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C	0°C~ 60°C
I/O Expansion		PCIe5.0*1,PCIe4.0*3, PCIe3.0*2(Q670/H670)/3(Z690) 2x RJ45,Line_in, Line_out, Mic_in 6x COM, 6x USB3.2, 6x USB2.0,PS/2, GPIO, LPT	2*PCIe16X(PCIe4.0 8X Signal)/1*PCIe16X(PCIe4.0 16X Signal),2*PCIe 8X (PCIe4.0 4X Signal)” 4x RJ45, Line_in, Line_out, Mic_in, 5x COM, 8x USB3.2, 4x USB2.0	PCI*4, PCIe16X, PCIe2X, PCIe1X,2x RJ45 Line_in, Line_out, Mic_in 10x COM, 4x USB3.2, 6x USB2.0,PS/2, GPIO, LPT, LPC	M.2 for WiFi, M.2 for 4G/5G PCI*4, PCIe16X, PCIe4X*2 2x RJ45 Line_in, Line_out, Mic_in 6x COM, 6x USB3.2, 6x USB2.0,PS/2, GPIO, LPT, LPC	M.2 for WiFi, PCI*2, PCIe16X, PCIe4X 2x RJ45 Mic_in, Line_out 6x COM, 4x USB3.2, 6x USB2.0,PS/2, GPIO, LPT, LPC	M.2 for WiFi, PCI*2, PCIe16X, PCIe4X(P–Cle1X Signal) 2x RJ45 Line–in, Line–out, Mic–in, 6xCOM, 8xUSB2.0: 4*ports+ 4*header, 4xUSB3.2, GPIO, LPT, LPC	2x RJ45, PCIe1X, PCIe4X*4, PCIe8X*2 Line_in, Line_out, Mic_in 6xCOM, 6xUSB3.2, 7xUSB2.0,PS/2, GPIO, LPT

Model				
   				
Mini ITX Motherboard	AL-10V2.0	ALN-10	EHL-10	TL-10
CPU	 Intel® Alder Lake-U/P Processor	Intel® Alder Lake-N Series Processor	Intel® Elkhart Lake Celeron, Pentium and Atom Processor	Intel® Tiger Lake-U Processor
Memory	 2x SO-DIMM DDR4 up to 64GB	1x SO-DIMM DDR4 up to 32GB	1x SO-DIMM DDR4 up to 32GB	2x SO-DIMM DDR4 up to 64GB
Display via	4x HDMI®, 1x LVDs/eDP,	1x HDMI®, 1x DP, 1x LVDs/eDP	1x HDMI®, 1x DP, 1x LVDs/eDP	4x HDMI®
Storage	 1x M.2_2280 NVMe,1x M.2_2242 SATA/4G 1x SATA3.0	1x M.2_2280/2242 SATA/4G, 1x SATA3.0	1x M.2_2280/2242 SATA/4G, 1x SATA3.0	1x M.2_2280 NVMe, 1x SATA3.0
Size	 170mm × 170mm	170mm × 170mm	170mm × 170mm	170mm x 170mm
Power	 19V DC-IN	12V/19V DC-IN	12V DC-IN/4pin power	12V/19V DC-IN
Operating Temp	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
I/O Expansion	 M.2 for WiFi, PCIe 4X, Nano SIM 2x RJ45 Line_out, Mic_in 6xCOM, 4xUSB3.2, 4xUSB2.0, GPIO	M.2 for WiFi, Support CNVi, PCIe4X(2x signal) 2x RJ45 Line_out, Mic_in 6x COM, 2x USB3.2, 6x USB2.0, USB Dongle, GPIO	M.2 for WiFi , PCIe4X(2X Signal), SIM optional,2x RJ45 Line_out, Mic_in 6x COM, 4x USB3.2, 4x USB2.0, GPIO, LPT	M.2 for WiFi, M.2 for 4G/5G PCIe2X,2x RJ45 Line_out, Mic_in 1x COM, 2x USB3.2, 6x USB2.0, LPC

			
WL-10	BW-10	HWM-10	FP-10
Intel® Whiskey Lake/Comet Lake-U Processor	Intel® Broadwell-U Celeron, Core Processor	Intel® Haswell Celeron Pentium Core Processor with HM86 Chipset	AMD Ryzen™ 5 2500U, V1605B Processor
2x SO-DIMM DDR4 up to 64GB	1x SO-DIMM DDR3L up to 8GB	2x SO-DIMM DDR3L up to 32GB	2x SO-DIMM DDR4 up to 64GB
1x HDMI®, 1x DP, 1x LVDs/eDP	1x HDMI®, 1x VGA, 1x LVDs/eDP	1x HDMI®, 1x VGA, 1x LVDs/eDP	4xDP1.4(DP1/LVDs/eDP Optional)
1x M.2_2242/2280 SATA, 2x SATA3.0(Only 1 if Celeron Onboard)	1x mSATA, 1x SATA3.0	1x mSATA, 1x SATA3.0	1xM.2 2280/2242 SATA/4G 1x SATA3.0
170mm ×170mm	170mm x 170mm	170mm x 170mm	170mm x 170mm
12V DC-IN/4pin power	12V DC-IN	12V DC-IN/4pin power	12V DC-IN
-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
M.2 for WiFi, PCIe4X 2x RJ45 Line_out, Mic_in 6x COM, 3x USB3.2, 5x USB2.0, GPIO, PS/2, LPT	Mini-PCle 2x RJ45 Line_out, Mic_in 10/6x COM, 2x USB3.2, 6x USB2.0, PS/2, GPIO	M.2 for WiFi, 1x RJ45, Line_out, Mic_in 4x COM, 4x USB3.2, 4x USB2.0, GPIO, PS/2	M.2 for WiFi, PCIe1X, PCIe4X 2x RJ45 Line_out, Mic_in 6x COM, 2x USB3.2, 8x USB2.0, GPIO, PS/2, LPT

Model				
   				
Mini ITX Motherboard	FP-610	ALD-15	JSL-15	CLD-15
CPU	 AMD Ryzen™ Mobile/ Embedded Series Processor	Intel® Alder Lake–S/Raptor Lake–S(LGA1700) Processor ≤65W with H610 Chipset	Intel® Jasper Lake Processor	Intel® 6th, 7th, 8th, and 9th Gen(LGA1151) Processor with H310C Chipset
Memory	 2x SO-DIMM DDR4 up to 64GB	2x SO-DIMM DDR4 up to 64GB	1x SO-DIMM DDR4 up to 16GB	2x SO-DIMM DDR4 up to 64 GB
Display via	4xDP(DP1/LVDs/eDP optional)	1x HDMI®, 1x VGA, 1x DP, 1x LVDs/eDP,	1x HDMI®, 1x LVDs/eDP, 1x VGA(optional with COM)	1x HDMI®, 1xLVDs, 1x VGA
Storage	 1x M.2_2280 NVMe/SATA, 1x M.2_2280/2242 SATA/4G, 1x SATA3.0	1x M.2_2280 NVMe/SA–TA(PCIe3.0 4X Signal), 1x SATA3.0	1x M.2_2242/2280 SATA, 1x SATA, eMMC optional	1x mSATA, 1x SATA3.0
Size	 170mm x 170mm	170mm x 170mm	170mm × 170mm	170mm x 170mm
Power	 19V DC–IN	19V DC–IN	12V DC–IN	19V DC–IN
Operating Temp	–20°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C
I/O Expansion	 M.2 for WiFi, PCIe4X 2x RJ45 Line_out, Mic_in 6x COM, 2x USB3.2, 6x USB2.0, GPIO, LPT	M.2 for WiFi support PCIe/CNVi/USB2.0 1xRJ45 Line_out, Mic_in JCOM, 4x USB3.2, 4x USB2.0	M.2 for WiFi 1x RJ45 Line_out, Mic_in 1x COM(optional with VGA), 2x USB3.2, 5x USB2.0	M.2 for WiFi 1x RJ45 Line_out, Mic_in 1x COM, 4x USB3.2, 4x USB2.0

   			
CFD-10	ALD-70	SKD-70	BYT-60
Intel® Coffee Lake(LGA1151) Processor with H310 Chipset	Intel®Alder iake/Raptor Lake–S (L–GA1700) Processor≤65W with H610 Chipset	Intel® Skylake/Kaby Lake(L–GA1151) with H110/B150/Z170 Chipset	Intel® Bay Trail Celeron, Atom Processors
2x SO-DIMM DDR4 up to 64 GB	2x SO-DIMM DDR4 up to 64GB	2x SO-DIMM DDR4 up to 32 GB	1x SO-DIMM DDR3L up to 8GB
2x HDMI® (Port +Pin), 1x DP, 1x LVDs/eDP,	1x HDMI®, 1x DP, 1x eDP,	1x HDMI®, 1x DP, 1x eDP optional	1x HDMI®, 1x LVDs/eDP,1x VGA
1x M.2_2242 SATA/4G, 2x SATA3.0	1x M.2_2280 NVMe/SATA, 2x SATA3.0	1x M.2_2242 SATA, 2x SATA3.0	1x mSATA, 1x SATA2.0, eMMC optional
170mm x 170mm	170mm x 170mm	170mm x 170mm	170mm x 170mm
19V DC–IN	24–PIN ATX+12V Auxiliary ATX Supply(2x4)	24–PIN ATX+12V Auxiliary ATX Supply(2x2)	12V DC–IN/4pin power
–20°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C
Mini–PCIe,SIM 2x RJ45 Line_out, Mic_in 6x COM, 4x USB3.2, 4x USB2.0, GPIO	M.2 for WiFi support CNVi, PCIe16X ,Line–in optional, 3x RJ45 Line_out, Mic_in 6x COM, 4x USB3.2, 5x USB2.0, GPIO, PS/2	M.2 for WiFi, PCIe1X, PCIe16X 3x RJ45 Line_out, Mic_in 5x COM, 4x USB3.2, 5x USB2.0, GPIO,PS/2, LPT	Mini–PCIe 2/1x RJ45 Line_out, Mic_in 6x COM, 1x USB3.2, 5x USB2.0, GPIO, PS/2, LPT

Model					
					
Single Board Computer	AL-35	ALN-35	WL-35	EHL-35V1.0	
CPU		Intel® Alder Lake-U Processor	Intel® Alder Lake-N Processor	Intel® Whiskey Lake/ Comet Lake-U Processor	Intel® Celeron Processor J6412
Memory		2xSO-DIMM DDR4 up to 64GB	1xSO-DIMM DDR4 up to 32GB	2x SO-DIMM DDR4 up to 64GB	1x SO-DIMM DDR4 up to 32GB
Display via		2x HDMI®, 1x LVDs/eDP	1x HDMI®, 1x DP,1x LVDs/eDP	1x HDMI®, 1x DP,1x eDP	1x HDMI®, 1x DP,1x LVDs/eDP
Storage		1x M.2_2242 SATA/4G,1x M.2_2280 NVMe, 1x SATA3.0	1x mSATA SSD/4G, 1x SATA3.0	1x M.2_2242 SATA/4G, 1x SATA3.0,	1x mSATA SSD/4G, 1x SATA3.0
Size		146mm x 102mm	146mm x 102mm	146mm x 102mm	146mm x 102mm
Power		12V-35V, 2-PIN DC-IN Phoenix connector	12V-35V DC-IN	12V/19V DC-IN	12V DC-IN
Operating Temp		-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
I/O Expansion		M.2 for WiFi, Support PCIe&CNVi, SIM optional 2x RJ45,CTIA 6x COM, 4x USB3.2, 4x USB3.0, GPIO	M.2 for WiFi, Support CNVi 2x RJ45 CTIA 6x COM, 4x USB3.2, 4x USB2.0, GPIO	M.2 for WiFi, Micro SIM 2x RJ45 CTIA 6x COM, 4x USB3.2, 2x USB2.0, GPIO, LPC	M.2 for WiFi 2xRJ45 CTIA 6xCOM, 4xUSB3.2, 4xUSB2.0, GPIO

 EHL-35V2.0  BYT-35V1.0  BYT-35V2.0  BW-35			
Intel® Celeron Processor J6412	Intel® Bay Trail BGA Processor	Intel® Bay Trail BGA Processor	Intel® Broadwell/Haswell-U Processor
1x SO-DIMM DDR4 up to 32GB	2x Onboard DDR3L up to 4GB	1x SO-DIMM DDR3L up to 8GB	1x SO-DIMM DDR3L up to 8GB
1x HDMI®, 1x DP,1x LVDs/eDP	1x HDMI®, 1x LVDs/eDP, 1x VGA,	1x HDMI®, 1x LVDs/eDP, 1x VGA,	1x HDMI®, 1x DP,1x LVDs/eDP
1x mSATA SSD/4G, 1x SATA3.0	1x mSATA, 1x SATA2.0, eMMC optional	1x mSATA, 1x SATA2.0	1x mSATA, 1x SATA3.0
146mm x 102mm	146mm x 102mm	146mm x 102mm	146x102mm
12V DC-IN	12V/19V DC-IN/4PIN Power/12V~36V optional	12V DC-IN/4pin power	12V/19V DC-IN
-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
M.2 for WiFi 2x RJ45 CTIA 6x COM, 4x USB3.2, 4x USB2.0, GPIO	Mini PCIe for WiFi/3G/4G Micro SIM 2x RJ45, CTIA, 6x COM, 1x USB3.2, 5x USB2.0, GPIO, LPC(optional)	Mini PCIe for WiFi/4G 2x RJ45 CTIA 6x COM, 1x USB3.2, 7x USB2.0, GPIO	M.2 for WiFi 2x RJ45 CTIA 6x COM, 3x USB3.2, 3x USB2.0, GPIO, LPC

Model	
	
Single Board Computer KL-35V2.0	
CPU	 Intel® Skylake/Kaby Lake-R Series Processor
Memory	 2x SO-DIMM DDR4 up to 32GB
Display via	1x HDMI®, 1x LVDs/eDP, 1x VGA
Storage	 1xmSATA, 1xSATA3.0 FPC
Size	 146mm x 102mm
Power	 9V-35V DC-IN
Operating Temp	-20°C~ 60°C
I/O Expansion	M.2 for WiFi, Nano SIM, 2x RJ45 CTIA 6xCOM, 4xUSB3.2, 4xUSB2.0, GPIO

Model			
  			
System on Module SOM-MTL95 TL-37 WL-37			
CPU	 Intel® Meteor Lake U/H Core Ultra 5/7 Series Processor with NPU	Intel® Tiger Lake-U Celeron and Core processor	Intel® Whiskey Lake -U Celeron and Core Processor
Memory	 2x SO-DIMM DDR5 up to 96 GB	Dual channel DDR4 up to 64GB	Dual Channel SO-DIMM DDR4 up to 64GB
Display via	3xDDI(HDMI/DP) 1x LVDs/eDP	Integrated graphics, 1x eDP interface	Integrated graphics, 1x eDP interface
Storage	 2 x SATA3.0	/	/
Size	 95mm x 95mm	125mm x 105.16mm	125mm x 105.16mm
Power	 ATX: Vin, VSB; AT: Vin	12V power input by CONN1, CONN2	12V DC input
Temperature	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
I/O Expansion	 2xRJ45, 2xCOM, 2xUSB4/TBT4, / 4xUSB3.2, 8xUSB2.0, GPIO, LPC, PEG (H Series): PCIe, 16 lanes, Bifurcate to 1 x8, 2 x4 PEG (U Series): PCIe, 8 lanes, Bifurcate to 2 x4PCIe: PCIe, Up to 8 lanes & Up to 8 end devices	/	

Model		
		
Core Boards /Customized Boards		
	BYT-33	FP-20
CPU	 Intel® Bay Trail Celeron J1900 Processor	Ryzen™ V1605B Processor
Memory	 1x SO-DIMM DDR3L up to 8GB	2x SO-DIMM DDR4 up to 64GB
Display via	1x VGA	2x HDMI®, 1x VGA, 1x DVI-D
Storage	 1x mSATA/SATA	1x M.2_2242/2280 NVMe/ SATA, 1x SATA3.0
Size	 238mm x 146mm	170mm x 170mm
Power	 12V DC-IN	12V/19V DC-IN
Temperature	-20°C~ 60°C	-20°C~ 60°C
I/O Expansion	 Mini-PCIe, PCIe4X(2X Signal) 6xRJ45 6/2xCOM 6xUSB2.0, GPIO	M.2 for WiFi 2x RJ45 Line_out, Mic_in, Line_in 6x COM, 3x USB3.2, 8x USB2.0, GPIO,

03

SYSTEM

Ultra-Compact Mini PC

Mini PC

Industrial Box PC

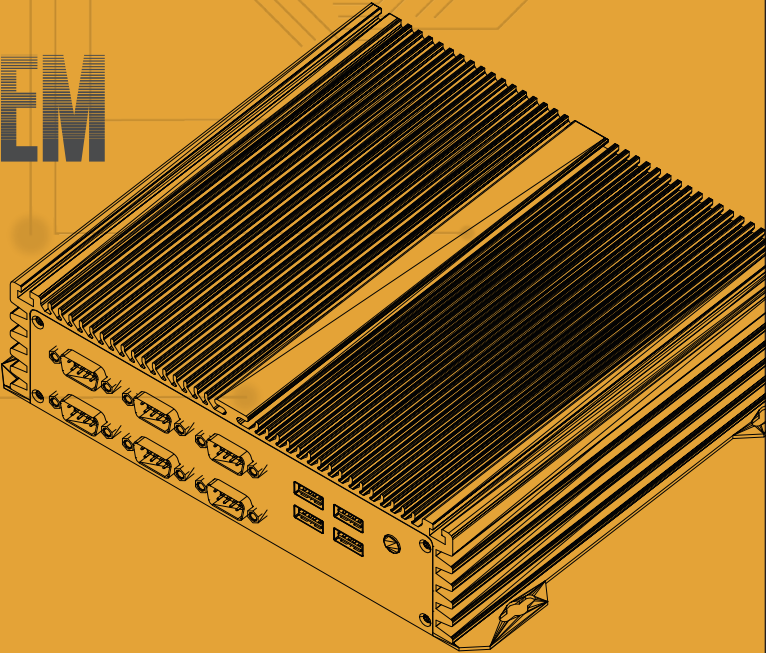
Edge Computing

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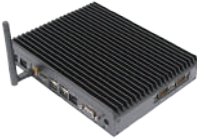
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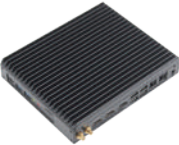
Model					
					
Ultra-Compact Mini PC		MTN-AL50	MTN-ALN50	MTN-BW50	MTN-FP50
CPU		Intel® Alder Lake-P/Raptor Lake-P Series	Intel® Alder Lake-N Series Processor	Intel® Broadwell/Haswell Processor	AMD Ryzen™ Mobile Processor
Memory		2x SO-DIMM DDR5 up to 64 GB	1x SO-DIMM DDR4 up to 32 GB	2x SO-DIMM DDR3L up to 16 GB	2x SO-DIMM DDR4 up to 64 GB
Display via		2x HDMI® 2.0, 1x DP1.4(USB-C)	2x HDMI® 2.0, 1x DP1.4(USB-C)	2x HDMI® 2.0	2x HDMI® 2.0
Storage		1xM.2_2280 NVMe (PCIe4.0), 1xSATA3.0	1xM.2_2280 SATA, 1xSATA FPC, eMMC optional	1xM.2 2280 SATA/NVMe, 1x SATA3.0	1x SATA3.0, 1xM.2 2280 SATA/NVMe
Size		128mm x 130mm x 51.5mm	127mm x 129mm x 48 mm	128mm x 130mm x52mm	128mm x 130mm x 52mm
Power		19V/20V DC input	12V/19V DC input	12V DC input	12V DC input
Temperature		0°C~ 50°C	0°C~ 50°C	0°C~ 50°C	0°C~ 50°C
I/O Expansion		M.2 for WiFi, Supports CNVi, 2xRJ45, CTIA, 2xUSB3.2, 2xUSB2.0, 1xUSB-C	M.2 for WiFi, supports PCIe, USB&CNVi, 2xRJ45, CTIA, 3xUSB3.2, 1xUSB2.0, 1xUSB-C, Wired Control optional	M.2 for WiFi, 1xRJ45 , Line_out, Mic_in, 3xUSB3.2, 2xUSB2.0	M.2 for WiFi, 1xRJ45 Line_out, Mic_in 3xUSB3.2, 2xUSB2.0
Cooling		Active Cooling	Active Cooling	Active Cooling	Active Cooling

   			
MTN-FP650MTN-FP750MTN-JSL50MTN-TL50			
AMD Ryzen™ 4000/5000 Series Mobile Processor			
AMD Ryzen™ 6000/7000 Series Mobile Processor			
Intel ®Celeron Processor N5095/N5095A/N5105			
Intel® Tiger Lake Processor			
2x SO-DIMM DDR4 up to 64 GB	2x SO-DIMM DDR5 up to 64 GB	2x SO-DIMM DDR4 up to 32 GB	2x SO-DIMM DDR4 up to 64 GB
2x HDMI® 2.0, 1x DP1.4(USB-C)	2x HDMI® 2.0, 1x DP1.4(USB-C)	2x HDMI®2.0	2x HDMI® 2.0
1x M.2_2280 NVMe/SATA, 1x SATA3.0	1x M.2_2280 NVMe, 1x SATA FPC	1x M.2 for NVMe/SATA	1xM.2_2280 NVMe, 1xSA-TA3.0
128mm x 130mm x 52mm	128mm x 130mm x 52mm	128mm x 130mm x 52mm	128mm x 130mm x 52mm
12V/19V DC input	19V/20V DC input	12V DC input	12V/19V DC input
0°C~ 50°C	0°C~ 50°C	0°C~ 50°C	0°C~ 50°C
M.2 for WiFi 1xRJ45 Line_out, Mic_in 2xUSB3.2, 2xUSB2.0, 1xUSB-C	M.2 for WiFi, supports PCIe&USB, 1xRJ45 Line_out, Mic_in 3xUSB3.2, 1xUSB2.0, 1xUSB-C, Wired Control optional	M.2 for WiFi 1xRJ45 Line_out, Mic_in 2xUSB3.2, 2xUSB2.0, 1xUSB-C	M.2 for WiFi 1xRJ45 Line_out, Mic_in 2xUSB3.2, 2xUSB2.0, 1xUSB-C
Active Cooling	Active Cooling	Active Cooling	Active Cooling

Model				
   				
Ultra-Compact Mini PC				
MUC-5095NXN100NX6412NX6412-4L				
CPU	 Intel® Celeron Processor N5095/N5095A/N5105	Intel® Alder Lake-N Series Processor	Intel® Elkhart Lake J6412 Processor	Intel® Elkhart Lake J6412 Processor
Memory	 2x SO-DIMM DDR4 up to 32 GB	1x SO-DIMM DDR4 up to 32 GB	2x SO-DIMM DDR4 up to 32 GB	1x SO-DIMM DDR4 up to 32 GB
Display via	2x HDMI® 2.0	2x HDMI® 2.0, 1xDP1.4(USB-C)	2xHDMI® 2.0	2x HDMI® 2.0
Storage	 1xM.2_2280 NVMe/SATA	1xM.2_2280 SATA/4G, 1xSATA FPC,eMMC optional	1x M.2_2242/2280 SATA ONLY/4G, 1x SATA	1xM.2_2242/2280 SATA ONLY/4G, 1xSATA
Size	 128.7mm x 128.7mm x 41.5mm	127mm x 127mm x 45.6mm	127mm x 127mm x 37mm or 43.5mm	127mm x 127mm x 43.5mm
Power	 12V DC input	12V DC input	12V DC input	12V DC input
Temperature	0°C~ 50°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
I/O Expansion	 M.2 for WiFi 1xRJ45 Line_out, Mic_in 2xUSB3.2, 2xUSB2.0, 1xUSB-C	M.2 for WiFi, supports PCIe&USB. SIM 2xRJ45 , CTIA 3xUSB3.2, 1xUSB2.0, 1xType-C, COM optional, Wired Control optional	M.2 for WiFi, SIM 2xRJ45 CTIA 2xUSB3.2, 2xUSB2.0, 1xType-C, COM optional	M.2 for WiFi, SIM 4xRJ45 1xCOM, 2xUSB3.2, 2xUSB2.0
Cooling	Active Cooling	Passive Cooling	Passive Cooling	Passive Cooling

   			
DBYT-50T0-FP750T0-RL50MAX-N100			
Intel® Bay Trail ProcessorAMD Ryzen™ 6000/7000 Series Mobile ProcessorIntel® Alder Lake/Raptor Lake Series ProcessorIntel® Alder Lake N Processor			
1x SO-DIMM DDR3L up to 8 GB	2x SO-DIMM DDR5 up to 64 GB	2x SO-DIMM DDR5 up to 64 GB	1x SO-DIMM DDR4 up to 16 GB
1x mini-HDMI®, 1x VGA	1x HDMI®, 2x DP(1*DP+ 1*USB4)	1x HDMI®,1xDP1.4, 1x TBT4	2x HDMI® 2.0
1x mSATA, eMMC optional	2x M.2_2280 NVMe	1x M.2_2280 SATA/N-VMe(Pcie3.0) 1x M.2_2280 NVMe(Pcie4.0)	1xM.2_2280 NVMe(Pcie3.0 4X)/SATA 1xM.2_2280 NVMe(Pcie3.0 1X)
127mm x 127mm x 30mm	135mm x 127mm x 55mm	127mm x 135mm x 55mm	120mm x 120mm x 35.5mm
19V DC input	19V/20 DC input	19V/20V DC input	AC-JACK (Input:100-240V~, 50/60Hz,1.5A, Output: 12V/3.75A)
-20°C~ 60°C	0°C to 50°C	0°C~ 50°C	-10°C~ 45°C
Mini-PCIe, TF Slot, SIM Slot 1xRJ45 CTIA 1xUSB3.2, 4xUSB2.0	M.2 for WiFi (PCIe&USB) 1xRJ45 CTIA, 2xUSB3.2, 1xUSB2.0, 2xUSB-C	1x M.2 Slot for WiFi and Bluetooth, Support CNVi 1xRJ45 CTIA 2xUSB3.2, 1xUSB2.0, 1xUSB-C, 1xTBT4	M.2 for WiFi and Bluetooth. 2xRJ45 CTIA 3xUSB3.2, 1xUSB2.0
Passive Cooling	Active Cooling	Active Cooling	Active Cooling

Model				
				
Mini PC	VBR-30	VBYT-30	VBYT-31	VHBYT-30
CPU	Intel® Braswell Processor	Intel® Bay Trail Processor	Intel® Bay Trail Processor	Intel® Bay Trail Processor
Memory	2x SO-DIMM DDR3L up to 8 GB	2x SO-DIMM DDR3L up to 8 GB	1x SO-DIMM DDR3L up to 8 GB	2x SO-DIMM DDR3L up to 8 GB
Display via	2x HDMI®	1x VGA, 1x HDMI®	1x VGA	1x HDMI®,1x VGA
Storage	1xSATA, 1xmSATA, eMMC optional	1xSATA3.0, 1xmSATA	1xSATA, 1xmSATA	1xSATA3.0, 1xmSATA
Size	151mm x 191mm x 27mm	150mm x 190mm x 29mm	150mm x 190mm x 29mm	191mm x 151mm x 34mm
Power	12V/19V DC input	12V /19 V DC-in	12V DC IN/9-36V optional	19V DC input
Operating Temp	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
I/O Expansion	Mini-PCIe, SIM Slot 1xRJ45 or 3xRJ45 Line_out, Mic_in 2xCOM, 2xUSB3.2, 4xUSB2.0	Mini-PCIe, SIM Slot(Internal) 3xRJ45/1xRJ45 Line_out, Mic_in 2xCOM, 1xUSB3.2, 5xUSB2.0,	Mini-PCIe, SIM Slot(Internal) 6xRJ45 CTIA 1xCOM, 4xUSB2.0	Mini-PCIe, SIM Slot(Internal) 3xRJ45 Line_out, Mic_in 2xCOM, 1xUSB3.2, 5xUSB2.0
Cooling	Passive Cooling	Passive Cooling	Passive Cooling	Passive Cooling

			
VHEHL-30	VHFP-30	VHHW-10	VHWL-30
Intel® Elkhart Lake J6412 Processor	AMD Ryzen™ Processor	Intel® Broadwell Processor	Intel® Whiskey Lake-U/Com-et Lake-U Processor
2x SO-DIMM DDR4 up to 32GB	2x SO-DIMM DDR4 up to 32 GB	1x SO-DIMM DDR3L up to 8 GB	2x SO-DIMM DDR4 up to 64 GB
3x HDMI® 2.0	1x DP, 1x HDMI®	1x HDMI®,1x mini-HDMI®	1x DP, 1x HDMI® , 1x mini HDMI®
1x M.2 2280 NVMe(PCIe2X Signal)/SATA 1xM.2 2242/2280 SATA/4G	1x M.2 2280 SATA/NVME 1x M.2 2242 SATA/4G	1x mSATA, 1x SATA3.0	1xM.2 2280 SATA/NVME 1xM.2_2242 SATA/4G
191mmx151mmx34mm	191mm x 151mm x 34mm	191mm x 151mm x 34mm	191mm x 151mm x 34mm
12V/19V DC IN /9-35V optional	12V/19V DC input	19V DC input	19V DC input
-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
M.2 for WiFi, SIM 2xRJ45 Line_out, Mic_in 1xCOM by default, 2xCOM optional 2xUSB3.2, 4xUSB2.0, 1xType-C	M.2 for WiFi, SIM 2xRJ45 Line_out, Mic_in 1xCOM, 2xUSB3.2, 4xUSB2.0, 1xType-C	Mini-PCIe 2xRJ45 Line_out, Mic_in 1xCOM, 2xUSB3.2, 4xUSB2.0	M.2 for WiFi, SIM 2xRJ45 Line_out, Mic_in 1xCOM 2xUSB3.2, 4xUSB2.0
Passive Cooling	Passive Cooling	Passive Cooling	Passive Cooling

Model				
				
Mini PC	FX1605	FXTL-10	FXJSL-15	FXH310C
CPU	 AMD Ryzen™ V1605B Processor	Intel® Tiger Lake-U Processor	Intel® Jasper Lake Processor	Intel® 6th,7th, 8th, 9th Gen Processor
Memory	 2x SO-DIMM DDR4 up to 32 GB	2x SO-DIMM DDR4 up to 64 GB	1x SO-DIMM DDR4 up to 16GB	2x SO-DIMM DDR4 up to 64 GB
Display via	4x DP	4x HDMI®	1xVGA(optional with COM) , 1xHDMI®	1xVGA, 1xHDMI®
Storage	 1xM.2_2242 SATA/4G or 1xM.2_2280 SATA, 1xSA-TA3.0	1xM.2_2280 NVMe , 1xSATA3.0	1xM.2_2242/2280 SATA, 1xSATA	1xSATA3.0, 1xmSATA
Size	 208mm x 190mm x 45mm	208mm x 190mm x 45mm	208mm x 190mm x 45mm	208mm x 190mm x 45mm
Power	 12V DC input	12V DC input	12V/19V DC input	19V DC input
Operating Temp	0°C~ 50°C	0°C~ 50°C	0°C~ 50°C	0°C~ 50°C
I/O Expansion	 M.2 for WiFi 2xRJ45 2xLine_out, 2xMic_in 2xCOM, 2xUSB3.2, 4xUSB2.0,	M.2 for WiFi, M.2 for 4G/5G PCIe2X 2xRJ45 2xLine_out, 2xMic_in 1xCOM, 2xUSB3.2, 4xUSB2.0	M.2 for WiFi 1xRJ45 2xLine_out, 2xMic_in 4xUSB3.2, 2xUSB2.0, COM optional: VGA will be replaced	M.2 for WiFi 1xRJ45 2xLine_out, 2xMic_in 4xUSB3.2, 2xUSB2.0,
Cooling	Active Cooling	Active Cooling	Active Cooling	Active Cooling

			
SXRL-20	SXA-6412	SXC-ALN30	SXC-ARL30
Intel® Alder Lake/Raptor Lake-U Processor	Intel® Elkhart Lake Processor	Intel® Alder Lake N Processor	Intel® Meteor Lake/Arrow Lake with NPU Processor
2x SO-DIMM DDR4 up to 64GB	2x SO-DIMM DDR4 up to 64 GB	1x SO-DIMM DDR4 up to 32 GB	2x SO-DIMM DDR5 up to 96 GB
4x HDMI® -OUT, 1x HDMI-IN.(Optional Depends on the CPU Model.)	3x HDMI® 2.0	3x HDMI® 2.0	4x HDMI® 2.0, 1x USB-C(DP1.4)
1x M.2 2280 Slot for NVMe/ SATA SSD 1x M.2 2280 Slot for NVMe SSD	1xM.2_2280 for SATA , 1xM.2_2280 SATA/NVMe(P-Cle2X Signal)	1x M.2_2242/2280 Key_M SATA/NVMe(PCIe X1) , 1x M.2_2242/2280 Key_B SATA/NVMe(PCIe X1) or 4G Module	1x M.2_2280 for NVMe , 1x M.2_2280 for SATA /4G
280mm x 195mm x 28mm	165mm x 150mm x 39.5mm	190mm x 150mm x 35mm	190mm x 150mm x 35mm
19V DC input, Phoenix-2Pin(Optional)	PoE input or 19V DC-IN	12V/19V DC-IN (9-35V Optional)	19V DC-IN/9-36V Phoenix-2PIN
- 20°C to 60°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
M.2 for WiFi, M.2 for 4G/5G SIM, 2xRJ45, 2xUSB3.2, 1xUSB2.0, 1xUSB-C 1xCOM(Console)	M.2 for Wi-Fi and Bluetooth 2xRJ45 CTIA 1xCOM, 4xUSB 3.2, GPIO, I2C, Wired Control	1x M.2 for Wi-Fi and Bluetooth, support PCIe and USB. Nano SIM, 2xRJ45 CTIA 2x COM, 4xUSB3.2, 2xUSB2.0, GPIO, Wired Control	M.2 for Wi-Fi and Bluetooth, support CNVi, PCIe & USB. Nano SIM, 2xRJ45 CTIA 2x COM, 4xUSB3.2, 2xUSB2.0, 1xUSB-C,Wired Control
Passive Cooling	Passive Cooling	Passive Cooling	Passive Cooling

Model	
	
Industrial Box PC IXH-KL35	
CPU 	Intel® Skylake/Kabylake-R Processor
Memory 	2x SO-DIMM DDR4 up to 32 GB
Display via	1x HDMI® , 1x VGA
Storage 	1x mSATA / 4G Module, 1x SATA3.0 FPC
Size 	205mm x 125mm x 70.5mm
Power 	9V-35V DC-IN
Temperature	-20°C~ 60°C
I/O Expansion 	M.2 for Wi-Fi and Bluetooth 2xRJ45 CTIA 6xCOM, 4xUSB3.2, 4xUSB2.0,GPIO, optional, Wired Control
Cooling	Passive Cooling

Model			
   			
BXTL-10DT-8803H-E1DT-8823H-B1DT-8853H-E4			
Intel® Tiger Lake-U Processor	Intel® Haswell Processor with B85 Chipset	Intel® 6th/7th/8th/9th Gen CPU (≤ 45W) with Q170 Chipset	Intel® 12th/13th Gen Processor with Z690 Chipset
2x SO-DIMM DDR4 up to 64 GB	2x SO-DIMM DDR3L up to 16GB	Dual channel SO-DIMM DDR4 up to 64 GB	2x SO-DIMM DDR5 up to 64 GB
4x HDMI®	1xVGA, 1xDP, 1xHDMI®	1x HDMI®, 1x VGA , 1x DP	1x VGA, 1x DP, 1x HDMI®
1xM.2_2280 NVMe , 1xSATA3.0	1xM.2_2280 SATA, 2xSATA	1xM.2_2280 SATA, 2xSATA	M.2 2280 forNVMe/SATA SSD,M.2 2242/2252 for SATA/4G/5G,SATA
299mm x 200mm x 52.2mm	227.5mm x220mm x125mm	227.5mm x220mm x84mm	266mm x 182.3mm x 262.8mm
12V/19V DC input	16V-36V DC input	16V-36V DC input	4PIN DC-IN (16V-36V/12V)
-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
M.2 for WiFi, M.2 for 4G/5G 2xRJ45 Line_out, Mic_in 2xUSB3.2, 4xUSB2.0	M.2 for WiFi, M.2 for 5G/4G 1*PCIe/PCI 3xRJ45 Line_out, Mic_in 6xCOM, 2xUSB3.2Port, 1xUSB3.2 Dongle Onboard, 6xUSB2.0 Ports, 2xUSB2.0-headers, GPIO, PS/2, Wire Control	M.2 for WiFi,M.2.for 4G/5G 3xRJ45 Line_out, Mic_in 6xCOM, 8xUSB3.2Port, 1xUSB3.2 Dongle Onboard, 2xUSB2.0 Ports, 2xUSB2.0-headers, GPIO, PS/2, Wire Control	M.2 for WiFi, 4*PCIe Slot 3xRJ45 Line_out, Mic_in 6xCOM, 8xUSB3.2Port, 1xUSB3.2 Dongle Onboard, 2xUSB2.0 Ports, 2xUSB2.0 headers, GPIO, PS/2, Wire Control
Passive Cooling	/	/	/

Model				
   				
Industrial Box PC				
	IXH-ALN35	IXH-AL35	IXALN-35	IXEHL-35V1.0
CPU	 Intel® Alder Lake-N Series Processor	Intel® Alder Lake/Raptor Lake U Processor	Intel® Alder Lake-N Processor	Intel® Elkhart Lake Processor
Memory	 1x SO-DIMM DDR4 up to 32 GB	2x SO-DIMM DDR4 up to 64 GB	1x SO-DIMM DDR4 up to 32 GB	1x SO-DIMM DDR4 up to 32 GB
Display via	1x HDMI® , 1x DP	2x HDMI®	1x DP, 1x HDMI®	1x DP, 1x HDMI®
Storage	 1x mSATA for SSD/4G, 1x SATA3.0	1x M.2_2242 SATA/4G, 1xM.2_2280 NVMe, 1xSA-TA3.0 FPC	1xmSATA, 1xSATA3.0	1xmSATA, 1xSATA
Size	 205mmx125mmx70.5mm	205mmx125mmx70.5mm	165mm x 125mm x 65mm	165mm x 125mm x 65mm
Power	 9V-35V DC-IN	9V-35V 2PIN DC-IN Phoenix Connector	12V-35V DC-IN/Phoenix optional	12V DC input/Phoenix optional
Operating Temp	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
I/O Expansion	 M.2 for WiFi, support CNVi, 2xRJ45 CTIA 6xCOM, 4xUSB3.2, 4xUSB2.0, GPIO, Wired control	M.2 for WiFi, support CNVi, 2xRJ45 CTIA 6xCOM, 4xUSB3.2, 4xUSB2.0, GPIO, Wired control	M.2 for WiFi, support CNVi 2xRJ45 CTIA 6xCOM, 4xUSB3.2, 4xUSB2.0, GPIO, Wired Control	M.2 for WiFi 2xRJ45 CTIA 6xCOM, 4xUSB3.2, 4xUSB2.0, GPIO, Wired Control
Cooling	Passive Cooling	Passive Cooling	Passive Cooling	Passive Cooling

			
IXEHL-35V2.0	IXBYT-35V1.0	IXBYT-35V2.1	IXWL-35
Intel® Elkhart Lake Processor	Intel® Bay Trail Processor	Intel® Bay Trail Processor	Intel® Whiskey Lake-U /Comet Lake – U Processor
1x SO-DIMM DDR4 up to 32 GB	2x Onboard DDR3L up to 4 GB	1x SO-DIMM DDR3L up to 8 GB	2x SO-DIMM DDR4 up to 64 GB
1x DP, 1x HDMI®	1x HDMI®, 1x VGA	1x HDMI®, 1x VGA	1x DP, 1x HDMI® , VGA optional
1xmSATA, 1xSATA	1xmSATA, 1xSATA2.0, eMMC optional	1xmSATA, 1xSATA2.0	1x M.2_2242 SATA/4G, 1xSATA3.0
165mm x 125mm x 65mm	165mm x 125mm x 65mm	165mm x 125mm x 65mm	165mm x 125mm x 65mm
12V DC input/Phoenix optional	12V/19V/4Pin/Phoenix optional	12V DC input/Phoenix optional	12V/19V DC input/Phoenix optional
-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
M.2 for WiFi 2xRJ45 CTIA 6xCOM, 4xUSB3.2, 4xUSB2.0, GPIO, Wired Control	Mini-PCle, Micro SIM 2xRJ45 CTIA 6xCOM, 1xUSB3.2, 5xUSB2.0	Mini-PCle, Micro SIM 2xRJ45 CTIA 6xCOM, 1xUSB3.2, 7xUSB2.0	M.2 for WiFi 2xRJ45 CTIA 6xCOM, 4xUSB3.2, 4xUSB2.0
Passive Cooling	Passive Cooling	Passive Cooling	Passive Cooling

Model					
Industrial Box PC					
	IXBW–35	DSAL–35	DXAL–10	DXALN–10	
	CPU 	Intel Broadwell/Haswell–U Processor	Intel Alder Lake Processor Core i5–1235U	Intel Alder Lake–U Processor	Intel Alder Lake N Series Processor
	Memory 	1x SO–DIMM DDR3L up to 8 GB	2x SO–DIMM DDR4 up to 64GB	2x SO–DIMM DDR4 up to 64 GB	1x SO–DIMM DDR4 up to 32GB
	Display via	1x HDMI®, 1x DP, VGA optional	2xHDMI®	4x HDMI®	1x DP, 1x HDMI
Storage 	1xmSATA, 1xSATA3.0	1xM.2_2280 NVMe, 1xM.2_2242 SATA/4G, 1x SATA3.0	1xM.2_2280 NVMe, 1xSA–TA3.0	1xM.2 2242/2280 SATA/4G, 1xSATA3.0	
Size 	165mm x 125mm x 65mm	255mm x 165mm x 60mm	255mm x 200mm x 60mm	255mm x 200mm x 60mm	
Power 	12V/19V DC input/Phoenix optional	12V–35V DC input	19V DC input	12V/19V DC input	
Operating Temp	–20°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C	
I/O Expansion 	M.2 for WiFi 2xRJ45 CTIA 6xCOM, 3xUSB3.2, 5xUSB2.0, USB Dongle optional	M.2 for WiFi, supports PCIe&CNVi, SIM optional 2xRJ45 CTIA 6xCOM, 4xUSB3.2, 4xUSB2.0, GPIO	M.2 for WiFi, support CNVi 2xRJ45 Line_out, Mic_in 6xCOM, 4xUSB3.2, 4xUSB2.0	M.2 for WiFi, support CNVi, SIM optional 2xRJ45 Line_out, Mic_in 6xCOM, 2xUSB3.2, 6xUSB2.0	
Cooling	Passive Cooling	Passive Cooling	Passive Cooling	Passive Cooling	

			
DX6412	DXBYT–60	DXBW–10	BXAL–10
Intel® Elkhart Lake Celeron J6412 Processor	Intel® Bay Trail Processor	Intel® Haswell/Broadwell Processor	Intel® Alder Lake–U Processor
1x SO–DIMM DDR4 up to 32 GB	1x SO–DIMM DDR3L up to 8 GB	1x SO–DIMM DDR3L up to 8 GB	2x SO–DIMM DDR4 up to 64 GB
1x DP, 1x HDMI®	1x VGA, 1x HDMI®	1x VGA, 1x HDMI®	4x HDMI® 2.0
1xM.2_2280/2242 SATA/4G, 1xSATA3.0	1xSATA2.0, 1xmSATA	1xSATA3.0, 1xmSATA	1xM.2_2280 NVMe , 1xSATA3.0
255mm x 200mm x 60mm	255mm x 200mm x 60mm	255mm x 200mm x 60mm	299mm x 200mm x 52.2mm
12V DC input	12V DC input	12V DC input	19V DC input
–20°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C	–20°C~ 60°C
M.2 for WiFi, SIM optional 2xRJ45 Line_out, Mic_in 6xCOM, 4xUSB3.2, 4xUSB2.0	Mini–PCIe 2xRJ45 Line_out, Mic_in 6xCOM, 1xUSB3.2, 5xUSB2.0,	2xRJ45 Line_out, Mic_in 10xCOM, 2xUSB3.2, 6xUSB2.0,	M.2 for WiFi, PCIe 4x 2xRJ45 Line_out, Mic_in 4xUSB3.2, 2xUSB2.0
Passive Cooling	Passive Cooling	Passive Cooling	Passive Cooling

Model				
 MV-06  MV-06C  UMIF Series  UMIV				
Edge Computing				
CPU	Intel® Celeron/Whiskey Lake-U Processor	Intel® Whiskey Lake-U/Tiger Lake-U Processor	Intel® 8th/11th Gen Celeron, Core i3/i5/i7	Intel® 6th/7th/8th/9th Gen Core i3/i5/i7
Memory	2x SO-DIMM DDR4 up to 64 GB	2x SO-DIMM DDR4 up to 64 GB	2x SO-DIMM DDR4 up to 64 GB	2x SO-DIMM DDR4 up to 64 GB
Display via	1x DVI, 1x HDMI®	1x DVI, 1x HDMI®	1x DVI, 1x HDMI®	1x HDMI®
Storage	1xM.2 for SSD or 4G, 1x M.2 for 2280 SSD	1xM.2 for SSD or 4G, 1x M.2 for 2280 SSD	1xM.2_2280/2242 SATA SSD, 1xmSATA,Optional built-in 1M FRAM	1x M.2_2280 NVMe(PCIe 2X Signal)/SATA SSD, 1xSATA
Size	220mmx150mmx90mm	220mmx150mmx90mm	140mm x 200mm x 62mm	162mm x 200mm x 60mm
Power	24V DC input	24V DC input or 9~36V w/o PoE	24V DC-in	12V-24V DC-IN
Temperature	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C	-20°C~ 60°C
I/O Expansion	6xRJ45 4xCOM, 4xUSB3.0, 2xUSB2.0, PS/2, Wire Control	6xRJ45 4xCOM, 4xUSB3.0, 2xUSB2.0, PS/2, Wire Control	M.2 for Wi-Fi and Bluetooth, M.2 for 4G/5G, 1xMini PCIe 3xRJ45 2xCOM, 2xUSB3.2, 2xUSB2.0	2x Mini PCIe 6xRJ45 2xCOM, 2xUSB3.2, 2xUSB2.0
Cooling	Passive Cooling	Passive Cooling	Passive/Active	Active Cooling

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Intel® 11th Gen Celeron, Core i3/i5/i7	Intel® 12th Gen Alder Lake N
2x SO-DIMM DDR4 up to 32GB	1x SO-DIMM DDR4 up to 16GB
1x HDMI®	1x HDMI®
1x M.2_2280	1x M.2_2280 NVMe(PCIe 2X Signal)/SATA SSD, 1xSATA
143mm x 200mm x 60mm	155.5mm x 160mm x 50mm
12V-24V DC-IN	12V-24V DC-IN
-20°C~ 60°C	-20°C~ 60°C
2x Mini PCIe 8xRJ45 2xCOM, 2xUSB3.0, 2xUSB2.0	1x Mini PCIe 4xRJ45 2xCOM, 2xUSB3.0, 2xUSB2.0, GPIO
Active Cooling	Passive/Active